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September 2017

FDPF035N06B

N-Channel PowerTrench[®] MOSFET 60 V, 88 A, 3.5 m Ω

Features

- $R_{DS(on)}$ = 2.91 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 88 A
- Low FOM R_{DS(on)}*Q_G
- · Low Reverse Recovery Charge, Qrr.
- · Soft Reverse Recovery Body Diode
- Enables Highly Efficiency in Synchronous Rectification
- · Fast Switching Speed
- · 100% UIL Tested
- · RoHS Compliant

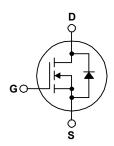
Description

This N-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench[®] process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor Drives and Uninterruptible Power Supplies
- · Renewable System





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FDPF035N06B-F152	Unit
V_{DSS}	Drain to Source Voltage	Drain to Source Voltage			V
V_{GSS}	Gate to Source Voltage			±20	V
1	Drain Current	- Continuous (T _C = 25°C, §	Silicon Limited)	88	Α
I _D	Diam Current	- Continuous (T _C = 100°C,	- Continuous (T _C = 100°C, Silicon Limited)		A
I _{DM}	Drain Current	- Pulsed	(Note 1)	352	Α
E _{AS}	Single Pulsed Avalanche Ene	Single Pulsed Avalanche Energy (Note 2)			mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	6.0	V/ns
D	Power Dissipation	(T _C = 25°C)		46.3	W
P_{D}	Fower Dissipation	- Derate Above 25°C	- Derate Above 25°C		W/oC
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +175	°C
T _L	Maximum Lead Temperature	for Soldering, 1/8" from Case fo	r 5 Seconds	300	°C

Thermal Characteristics

Symbol	Parameter	FDPF035N06B-F152	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDPF035N06B-F152	FDPF035N06B	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV_DSS	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60	-	-	V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	0.03	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48 V, V _{GS} = 0 V	-	-	1	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	-	4	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 88 \text{ A}$	-	2.91	3.5	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 88 A	-	176	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz	-	6035	8030	pF
C _{oss}	Output Capacitance		-	1685	2240	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	-	55	-	pF
C _{oss(er)}	Energy Related Output Capacitance	V _{DS} = 30 V, V _{GS} = 0 V	-	2619	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	76	99	nC
Q _{gs}	Gate to Source Gate Charge	$V_{DS} = 30 \text{ V}, I_{D} = 100 \text{ A},$	-	29	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10 V	-	12	-	nC
V _{plateau}	Gate Plateau Volatge	(Note 4)	-	5.2	-	V
Q _{sync}	Total Gate Charge Sync.	$V_{DS} = 0 \text{ V}, I_{D} = 50 \text{ A}$	-	67.3	-	nC
Q _{oss}	Output Charge	V _{DS} = 30 V, V _{GS} = 0 V	-	92.4	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	2.0	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	32	74	ns
t _r	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 100 \text{ A},$		-	33	76	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 4.7 Ω		-	56	122	ns
t _f	Turn-Off Fall Time		(Note 4)	-	23	56	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	88	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	352	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 88 A		-	-	1.25	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 100 A,	-	71	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	78	-	nC

- **Notes:**1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 3 mH, I_{AS} = 20 A, starting T_J = 25°C.
- 3. I $_{SD}$ \leq 100 A, di/dt \leq 200 A/ μ s, V_{DD} \leq BV $_{DSS}$, starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

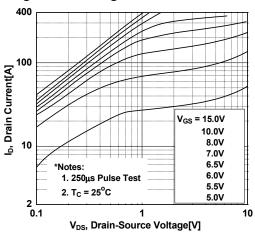


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

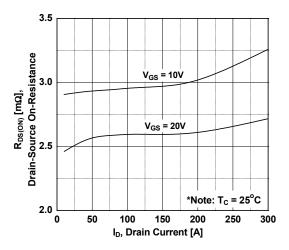


Figure 5. Capacitance Characteristics

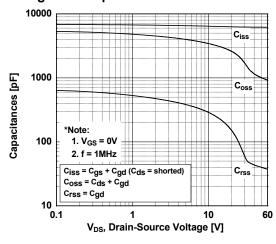


Figure 2. Transfer Characteristics

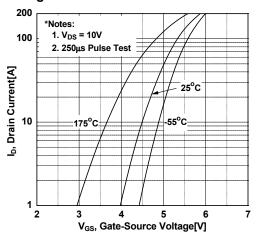


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

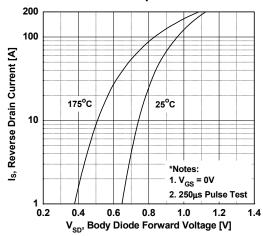
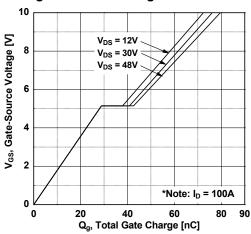


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

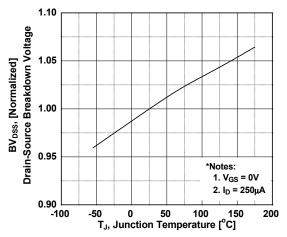


Figure 9. Maximum Safe Operating Area

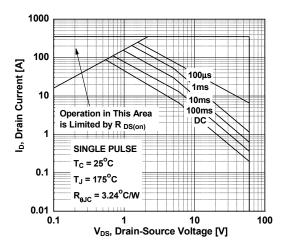


Figure 11. Eoss vs. Drain to Source Voltage

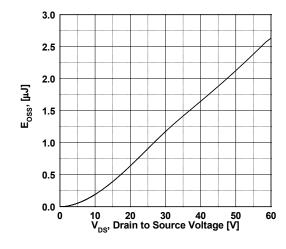


Figure 8. On-Resistance Variation vs. Temperature

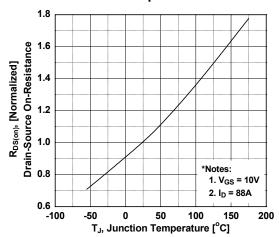


Figure 10. Maximum Drain Current vs. Case Temperature

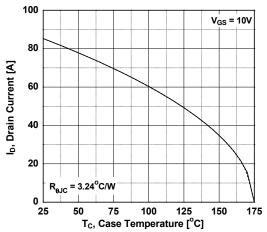
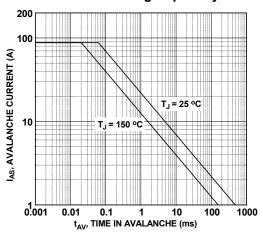
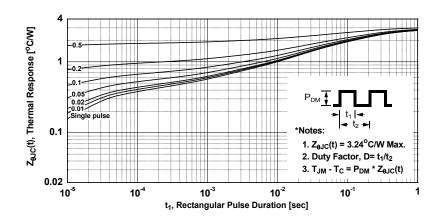


Figure 12. Unclamped Inductive Switching Capability



Typical Performance Characteristics (Continued)





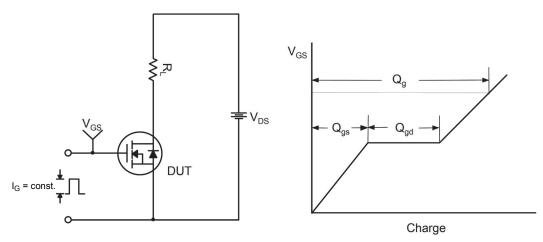


Figure 14. Gate Charge Test Circuit & Waveform

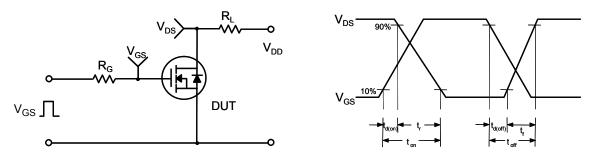


Figure 15. Resistive Switching Test Circuit & Waveforms

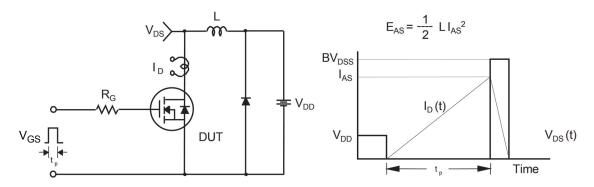
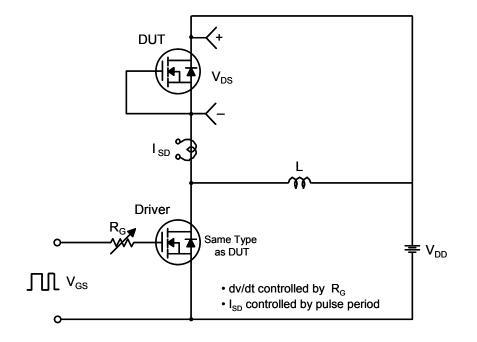


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



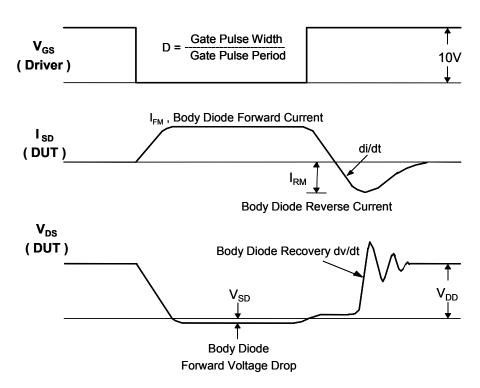


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

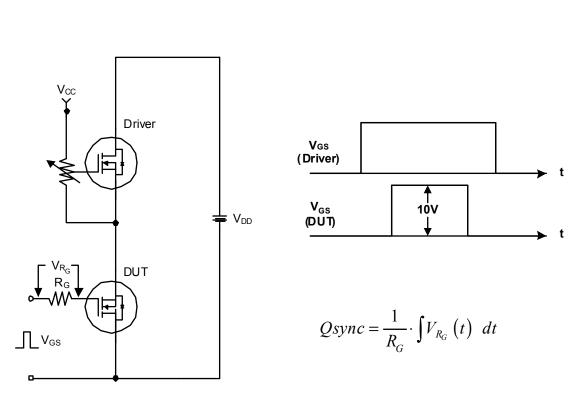


Figure 18. Total Gate Charge Qsync. Test Circuit & Waveforms

Mechanical Dimensions

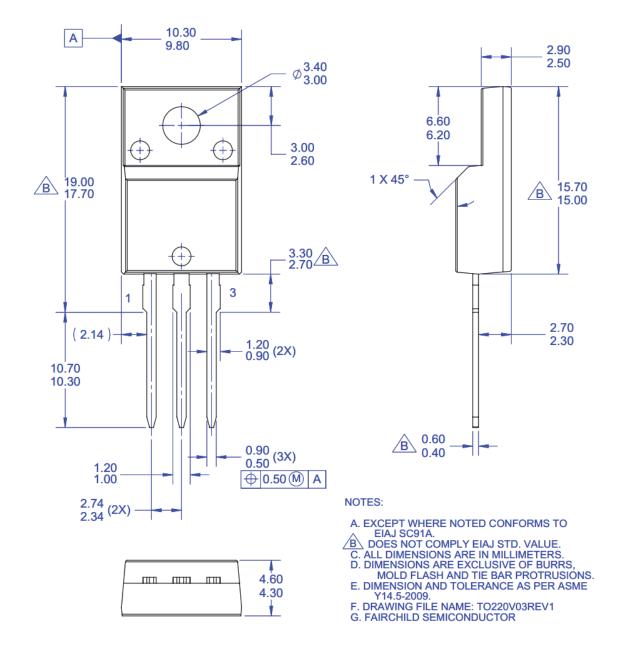


Figure 19. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Takcheong

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